CRMKBU0202A

P-Channel -20V, 2.9mΩ Typ. Power MOSFET

Description

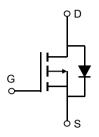
Features

• -20V, -90A

$$R_{DS(ON)}$$
 Typ = 2.9m Ω @ V_{GS} = -4.5 V

$$R_{DS(ON)}$$
 Typ = 3.8m Ω @ V_{GS} = -2.5V

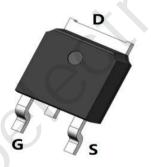
- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!

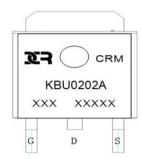




Application

- Load Switch
- PWM Application
- Power Management





Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKBU0202A	CRMKBU0202A	TO-252-3L	TAPING	13"	2500	25000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		-20	V
V_{GS}	Gate-to-Source Voltage		±12	V
	Continuous Drain Current	T _C = 25°C	-90	Α
I _D	Continuous Drain Current	T _C = 100°C	-54	Α
I _{DM}	Pulsed Drain Current (1)		-360	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		100	mJ
P_{D}	Power Dissipation	T _C = 25°C	52.5	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		2.38	°C/W
T_J, T_STG	Junction & Storage Temperature Range		-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -20V, V_{GS} = 0V$	-	-	-1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 12V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.4	-0.65	-0.95	V
_		$V_{GS} = -4.5V$, $I_D = -15A$	-	2.9	3.8	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = -2.5V, I_D = -10A$	-	3.8	4.9	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-(6700	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = -10V,$ f = 1MHz	X -	995	-	pF
C_{rss}	Reverse Transfer Capacitance	1 - 11VII 12		800	-	pF
Q_g	Total Gate Charge		9 -	100	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } -4.5V$ $V_{DS} = -10V, I_{D} = -15A$	-	15	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} = -10V, I _D = -13A	-	28	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime	.(0)	-	19	-	ns
t _r	Turn-On Rise Time	$V_{GS} = -10V, V_{DD} = -10V$	-	198	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	I_{D} = -13A, R_{GEN} = 2.7 Ω	-	282	-	ns
t_f	Turn-Off Fall Time		-	288	-	ns
Drain-So	urce Diode Characteristics and I	Max Ratings				
Is	Maximum Continuous Drain to Source D	iode Forward Current	-	-	-90	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	-360	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -15A	-	-	-1.2	V

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =-10V, V_G =-10V, R_G =25ohm, L=0.5mH, I_{AS} =-20A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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Test Circuit

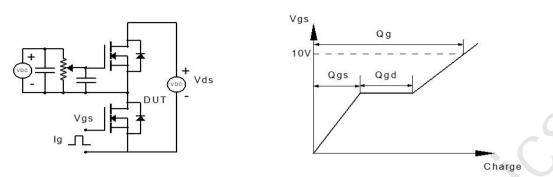


Figure 1: Gate Charge Test Circuit & Waveform

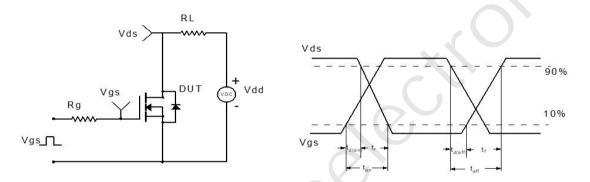


Figure 2: Resistive Switching Test Circuit & Waveform

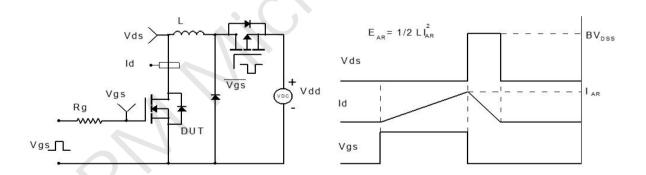


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

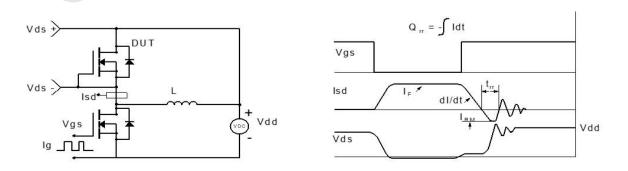
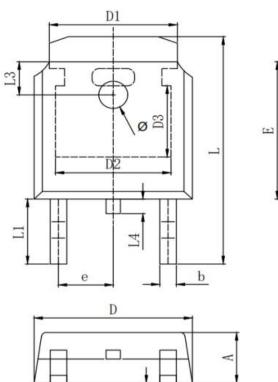


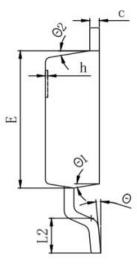
Figure 4: Diode Recovery Test Circuit & Waveform

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Package Mechanical Data(TO-252-3L)





SYMBOL	MILLIMETER				
SIMBOL	MIN	Typ.	MAX		
A	2. 200	2.300	2.400		
A1	0.000		0. 127		
b	0.640	0.690	0.740		
c(电镀后)	0.460	0. 520	0.580		
D	6.500	6.600	6. 700		
D1	5. 334 REF				
D2	4. 826 REF				
D3	3. 166 REF				
Е	6.000	6. 100	6. 200		
e	2. 286 TYP				
h	0.000	0.100	0. 200		
L	9. 900	10.100	10.300		
L1	2. 888 REF				
L2	1.400	1.550	1.700		
L3	1.600 REF				
L4	0.600	0.800	1.000		
ф	1.100	1. 200	1.300		
θ	0°		8°		
θ 1	9° TYP				
θ2	9° TYP				

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